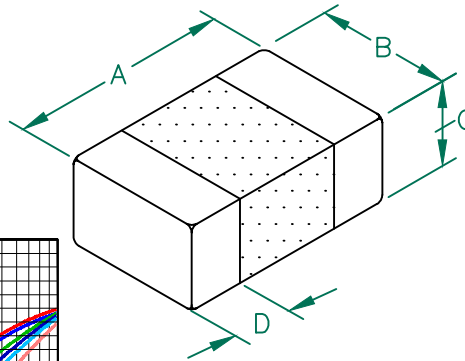


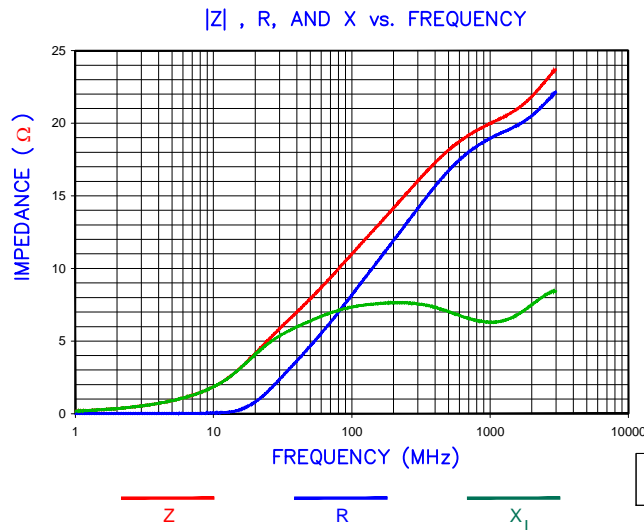
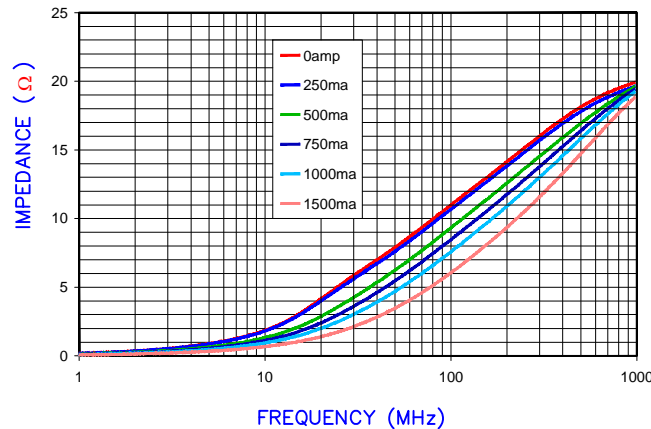
# MI0805K110R-10

## PHYSICAL DIMENSIONS:

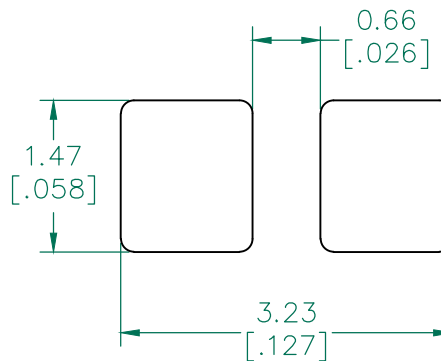
A	2.00 [.079]	$\pm$ 0.20 [.008]
B	1.25 [.049]	$\pm$ 0.20 [.008]
C	0.90 [.035]	$\pm$ 0.20 [.008]
D	0.51 [.020]	$\pm$ 0.25 [.010]



Z vs FREQUENCY  
IMPEDANCE UNDER DC BIAS



## LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension)

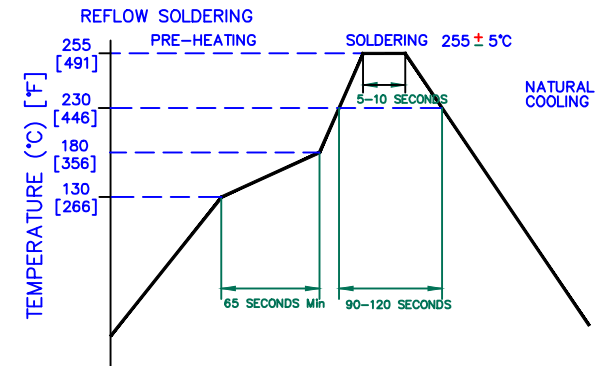
## ELECTRICAL CHARACTERISTICS:

Z @ 100MHz ( $\Omega$ )	DCR ( $\Omega$ )	Rated Current
Nominal	11	
Minimum	8	
Maximum	14	0.06
		1500 mA

## NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMP. RANGE:  $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ . (INCLUDING SELF-HEATING)

## RECOMMENDED SOLDERING CONDITIONS



## DIMENSIONS ARE IN mm [INCHES].

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<b>Laird</b>			
E	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU
D	CHANGE TO PAPER TAPE	03/04/10	JUN
C	UPDATE COMPANY LOGO	08/06/08	JRK
B	ADD ROHS & UPDATE COMPANY LOGO	08/28/07	JRK
A	ORIGINAL DRAFT	04/05/04	TMB
REV	DESCRIPTION	DATE	INT
PROJECT/PART NUMBER:		MI0805K110R-10	
DATE:	04/05/04	SCALE:	—
CAD #	MI0805K110R-10-E	TOOL #	—
REV	DESCRIPTION	DATE	INT
PART TYPE:		CO-FIRE	
DRAWN BY:		TMB	
SHEET:		1 of 1	



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